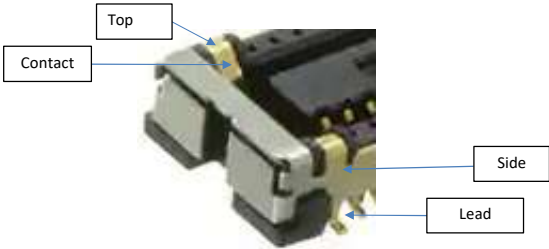
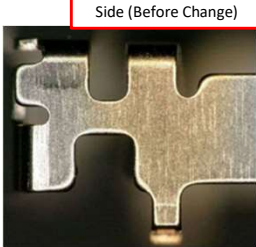
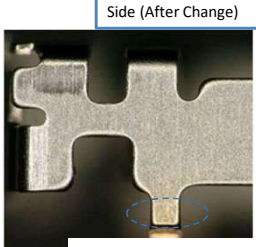
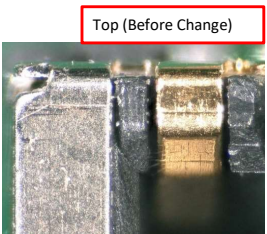
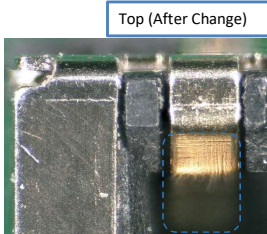
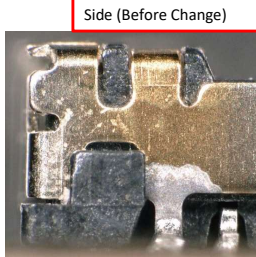
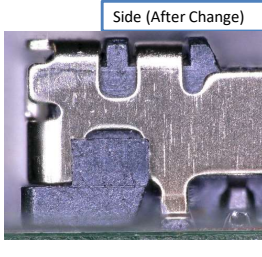


Attn.: _____

HIROSE ELECTRIC CO., LTD.
 2-6-3 Nakagawa Chuoh, Tsuzuki-ku, Yokohama, JAPAN

Product Change Notification

We are writing today to inform you that we will make some changes as shown in the subject for the reason described below.
 We will announce them in advance.

1	Products affected	DF40GB series *Please refer to the attachment for detailed product names.
2	Replacement product	There is no change in product code and product name.
3	Classification of change	Plating Improvement
4	Changes	<p>The gold plating appearance of the shield board will be changed. The current shield board plating technology applies gold plating on the lead, side, top and contact area of the shield in a straight line. As a result, there is a risk that solder will rise to the contact point on the top surface in case of the large amount of solder or the different reflow conditions from our recommendations. This time, we have established a processing technology that applies gold plating only to the lead and contact area, so we will implement this improvement to suppress the spread and reduce the risk of solder rise. Although there is a change in the appearance of the shield board, there is no change in product performance.</p>  <div style="display: flex; justify-content: space-around;"> <div style="text-align: center;">  <p>Side (Before Change)</p> </div> <div style="text-align: center;">  <p>Side (After Change)</p> <p>Lead Area (Gold plating)</p> </div> </div> <div style="display: flex; justify-content: space-around; margin-top: 10px;"> <div style="text-align: center;">  <p>Top (Before Change)</p> </div> <div style="text-align: center;">  <p>Top (After Change)</p> <p>Contact Area (Gold plating)</p> </div> </div> <div style="display: flex; justify-content: space-around; margin-top: 10px;"> <div style="text-align: center;">  <p>Side (Before Change)</p> </div> <div style="text-align: center;">  <p>Side (After Change)</p> </div> </div> <p>From the comparison photos before and after the change, it can be seen that there is gold plating spread on the side and top of the shield board before the change, and thus cause solder rise on the side after mounting. The improved product has suppressed gold plating spread and solder rise after mounting.</p>
5	Reason for change	To reduce the risk of solder rise
6	Schedule of change	We are planning to switch to the improved product from June 2023 onwards.

If you should have any questions, please feel free to contact a Hirose business representative.
 Your understanding and cooperation are highly appreciated.

■Product list PCN2022-12_Report on improvement of the shield board plating in our product DF40GB series

No	Current product		Replacement product	
	Product code	Part Number	Product code	Part Number
1	684-4194-3-51	DF40GB(1.5)-48DS-0.4V(51)	There is no change in product code and product name.	
2	684-4194-3-58	DF40GB(1.5)-48DS-0.4V(58)		
3	684-4198-4-51	DF40GB(1.5)-30DS-0.4V(51)		
4	684-4198-4-58	DF40GB(1.5)-30DS-0.4V(58)		